

## Stereo 330mW 8Ω Speak Driver With Mute

### Features

- Operating Voltage
  - Single Supply 3V to 7V
  - Dual Supply ±1.5V to ± 3.5V
- Depop Circuitry Integrated.
- High Signal-to-Noise Ratio 100dB
- High Slew Rate 5.5V/ms
- Low Distortion -66dB
- Output Power at 10% THD+N
  - into 8Ω 330mW
  - into 16Ω 200mW
- Large Output Voltage Swing
- Excellent Power Supply Ripple Rejection
- Low Power Consumption
- Short-circuit Elimination
- Wide Temperature Range
- No Switch ON/OFF Clicks
- Available in 8 pin SOP, TSSOP or PDIP Package

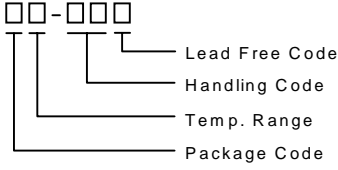

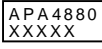
### Applications

- Portable Digital Audio
- Personal Computers
- Microphone Preamplifier
- CD ROM Player
- Headphone Amplifier

### General Description

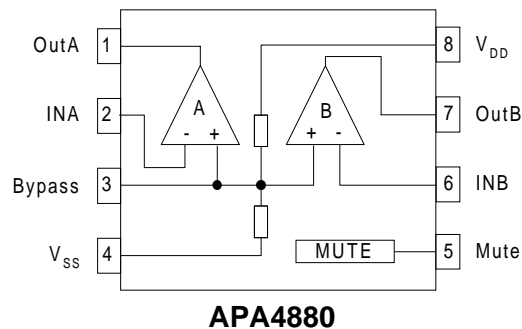
The APA4880 is an integrated class AB stereo head-phone amplifier contained in an SO-8 or a DIP-8 plastic package. The APA4880 is capable of delivering 330mW of max. output power to an 8Ω load with less than 10% (THD+N) from a 5V power supply. The device has been primarily developed for portable digital audio applications. Both of the depop circuitry and mute circuitry are integrated in the APA4880, that reduces pops and clicks noise during power up and when using the mute mode(high active).

### Ordering and Marking Information

<p>APA4880 <span style="font-family: monospace;">□□-□□□</span></p> 	<p>Package Code                  J : PDIP - 8    K : SOP - 8    O : TSSOP-8</p> <p>Temp. Range                  I : - 40 to 85 °C</p> <p>Handling Code                  TU : Tube            TR : Tape &amp; Reel</p> <p>Lead Free Code                  L : Lead Free Device    Blank : Original Device</p>
<p>APA4880 J : </p>	<p>XXXXX - Date Code</p>
<p>APA4880 K/O : </p>	<p>XXXXX - Date Code</p>

ANPEC reserves the right to make changes to improve reliability or manufacturability without notice, and advise customers to obtain the latest version of relevant information to verify before placing orders.

## Block Diagram



## Pin Function Description

Pin Name	No	I/O	Description
OUTA	1	O	Channel A output pin
INA	2	I	Audio input channel A
Bypass	3	I	Connect to voltage divider for internal mid_supply bias
VSS	4		Ground or negative supply voltage connection for circuitry.
Mute	5	I	mute mode control signal input, place entire IC in mute mode when held high, $I_{mute}=140\mu A$
INB	6	I	Audio input channel B
OUTB	7	O	Channel B output pin
VDD	8		Supply voltage input pin

## Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
$V_{DD}$	Supply Voltage	5	V
$T_{SC(O)}$	Output Short-Circuit Duration , at $T_A=25^\circ C$ , $P_{TOT}=1W$	20	S
$T_A$	Operating Ambient Temperature range	-40 to 85	$^\circ C$
$T_J$	Maximum Junction Temperature	150	$^\circ C$
$T_{STG}$	Storage Temperature Range	-65 to +150	$^\circ C$
$T_S$	Soldering Temperature , 10 seconds	260	$^\circ C$
$V_{ESD}$	Electrostatic Discharge	-3000 to 3000*1	V

Note : \*1. Human body model :  $C=100pF$  ,  $R=1500\Omega$  , 3 positive pulses plus 3 negative pulses

## Thermal Characteristics

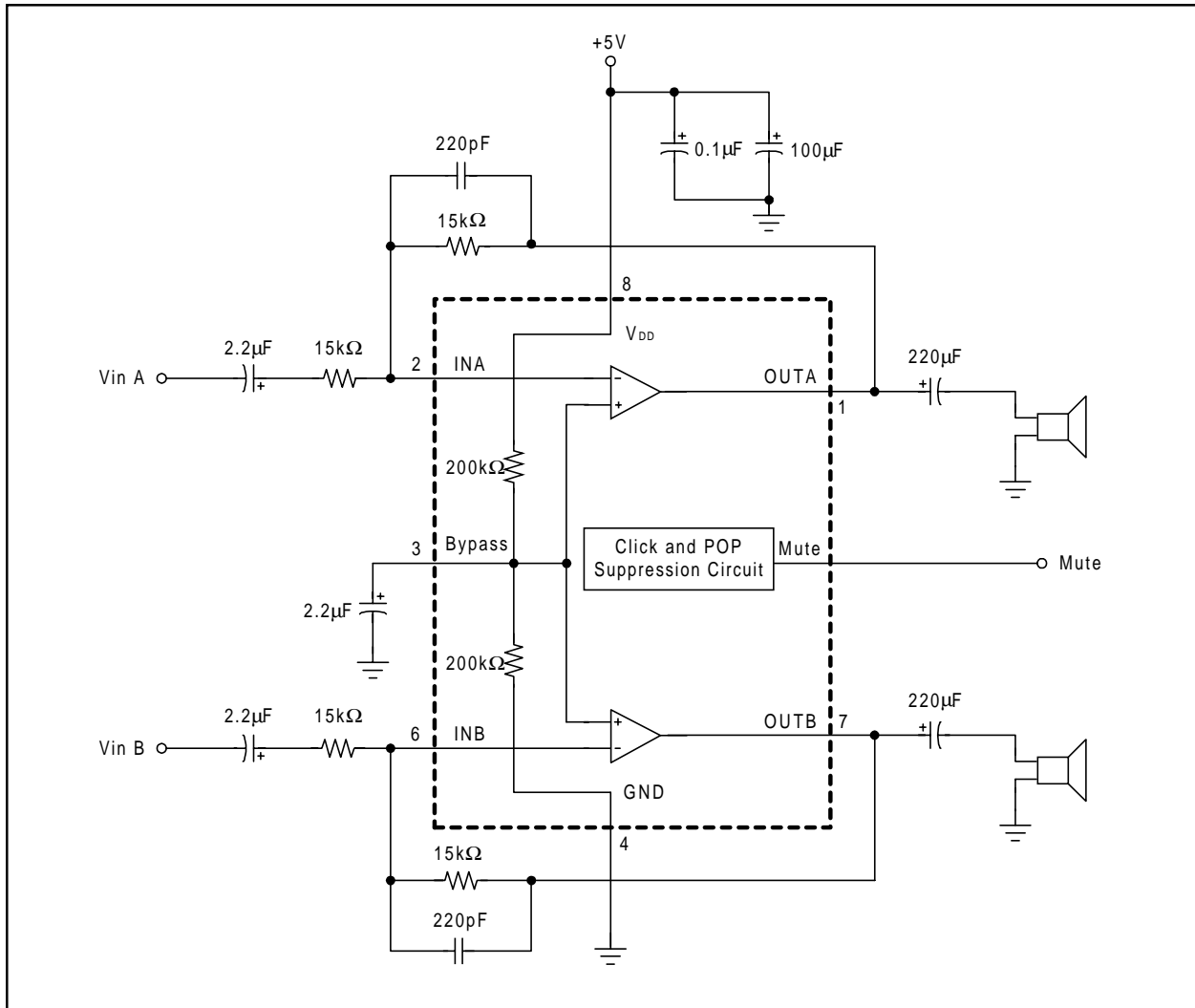
Symbol	Parameter	Value	Unit
R <sub>THJA</sub>	Thermal Resistance from Junction to Ambient in Free Air		
	SO-8	210	K/W
	TSSOP-8	220	
	PDIP-8	109	

## Electrical Characteristics

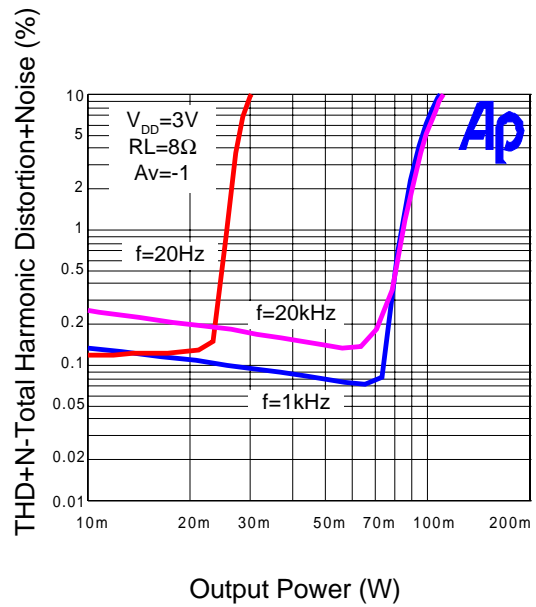
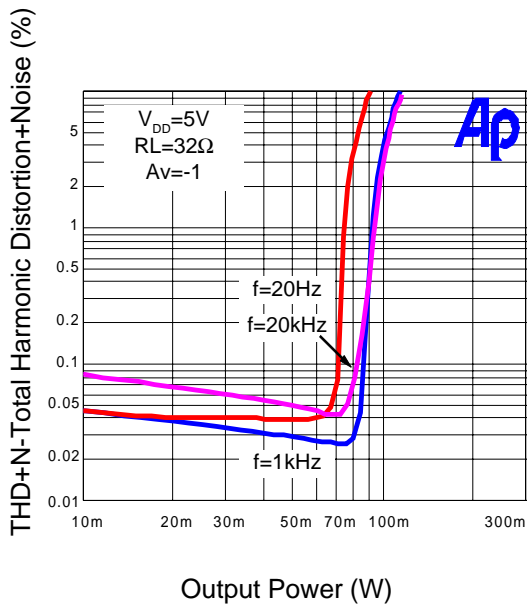
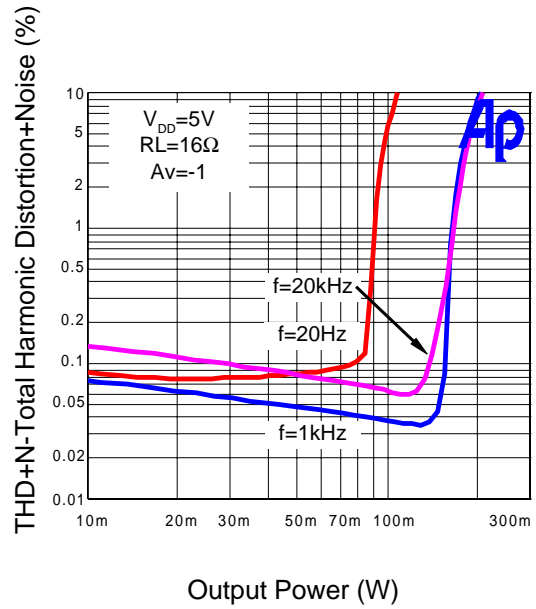
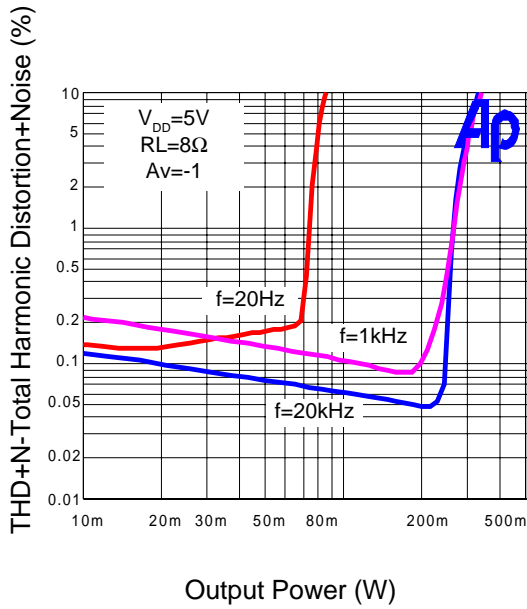
T<sub>A</sub>=25°C, V<sub>DD</sub>=5V, V<sub>SS</sub>=0V, f=1kHz (unless otherwise noted)

Symbol	Parameter	Test Conditions	APA4880			Unit
			Min.	Typ.	Max.	
I <sub>DD</sub>	Supply Current	No Load		3.0		mA
I <sub>MUTE</sub>	Mute Current	V <sub>PINS</sub>		140		uA
V <sub>I(OS)</sub>	Input Offset Voltage			5		mV
<b>AC Characteristics</b>						
(THD+N)/S	Total Harmonic Distortion plus Noise to Signal Ratio	P <sub>O</sub> =200mW, R <sub>L</sub> =8Ω, f=1kHz P <sub>O</sub> =120mW, R <sub>L</sub> =16Ω, f=1kHz P <sub>O</sub> =75mW, R <sub>L</sub> =32Ω, f=1kHz		0.05 0.04 0.03		%
P <sub>O</sub>	Output Power	(THD+N)/S=0.1%, f=1kHz R <sub>L</sub> =8Ω R <sub>L</sub> =16Ω R <sub>L</sub> =32Ω (THD+N)/S=10%, f=1kHz R <sub>L</sub> =8Ω R <sub>L</sub> =16Ω R <sub>L</sub> =32Ω		240 150 85 330 200 110		mW
PSRR	Power Supply Rejection Ratio	C <sub>S</sub> =2.2uF, V <sub>RIPPLE</sub> =200mV <sub>RMS</sub> , f=120Hz		50		dB
ATT	Mute attenuation	V <sub>in</sub> =1V <sub>rms</sub> , R <sub>L</sub> =8Ω		85		dB
Xtalk	Channel Separation	P <sub>O</sub> =200mV, R <sub>L</sub> =8Ω, C <sub>b</sub> =2.2uF		85		dB
G <sub>v</sub>	Open Loop Gain			100		dB
F <sub>g</sub>	Unity Gain Frequency			7		MHz
SR	Slew Rate			5.5		V/us
S/N	Signal to Noise Ratio	V <sub>in</sub> =1V <sub>rms</sub> , R <sub>L</sub> =8Ω		20		uV <sub>rms</sub>

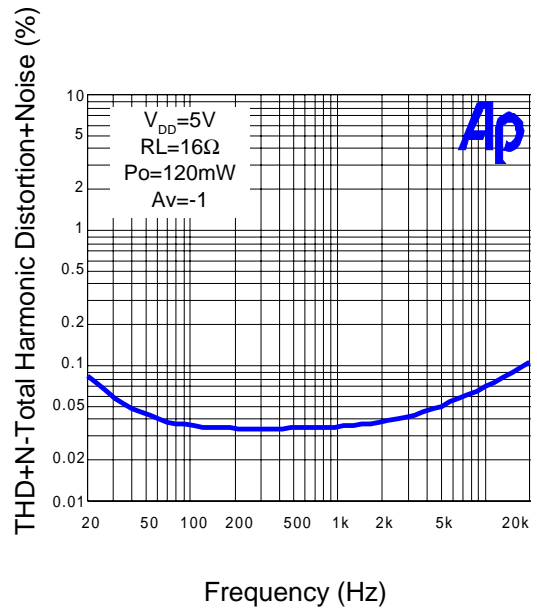
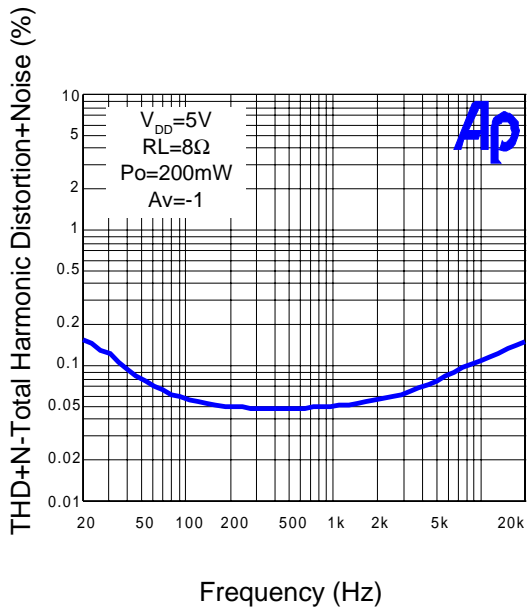
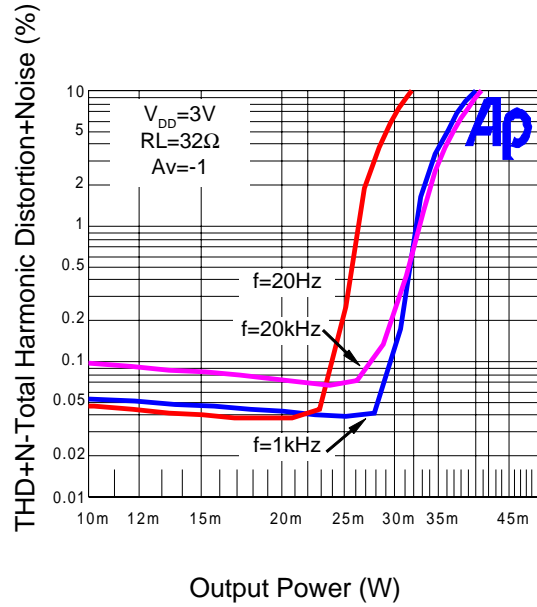
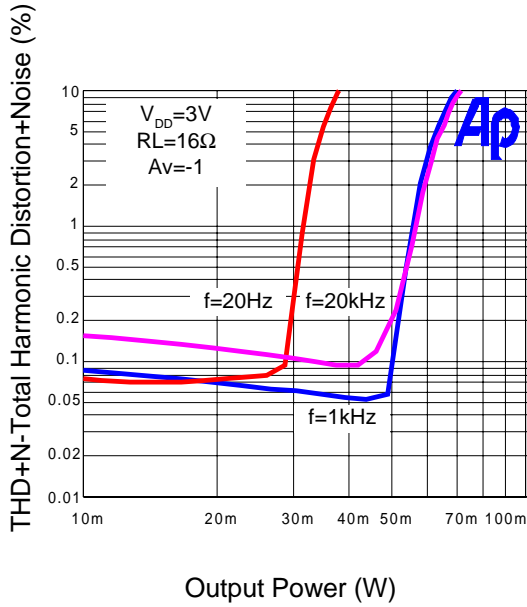
Test And Application Circuits



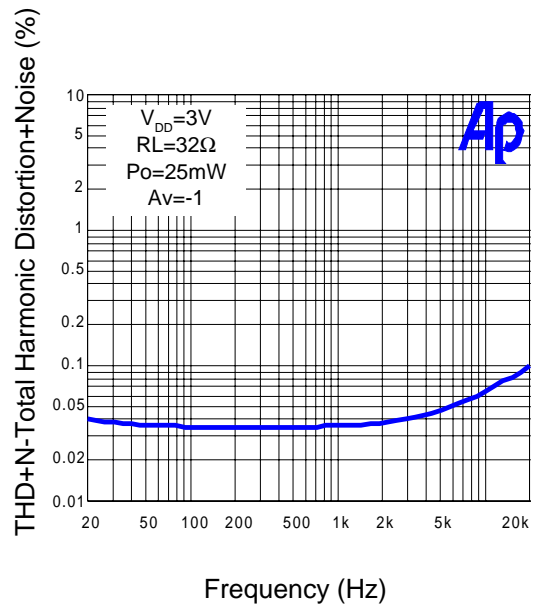
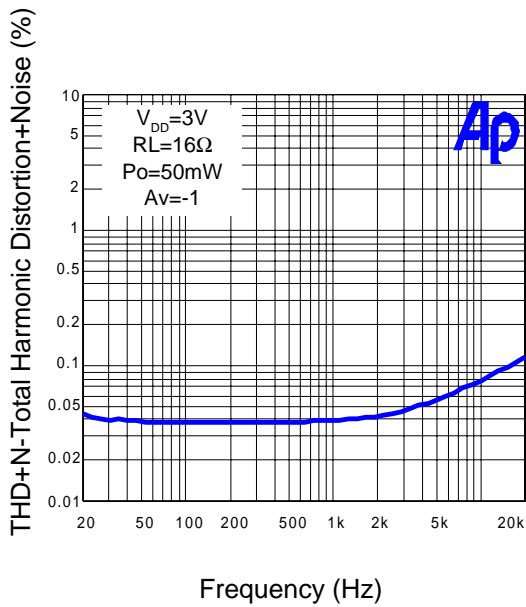
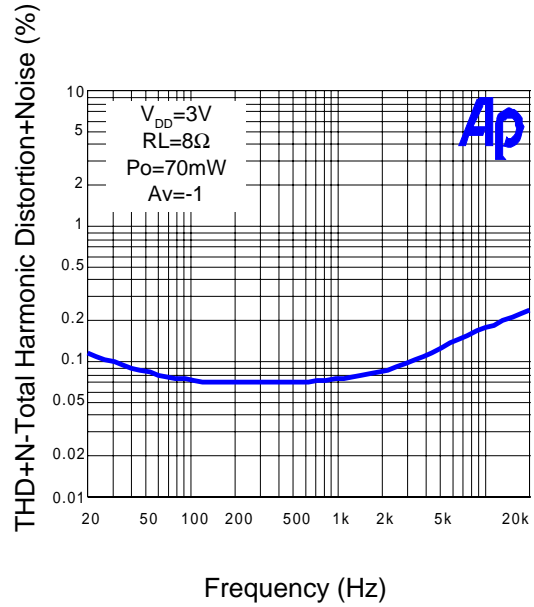
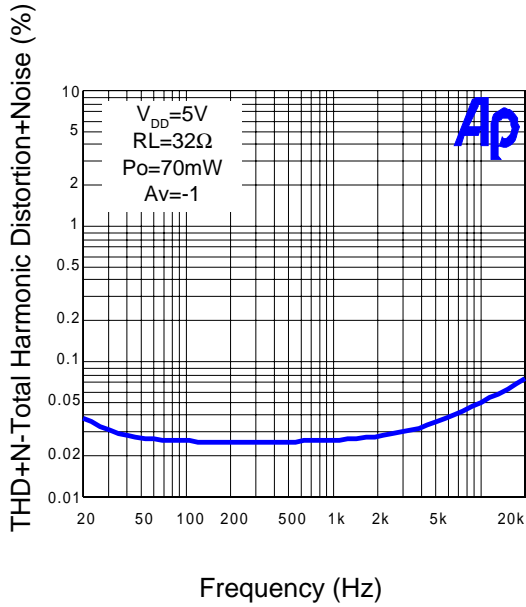
## Typical Characteristics



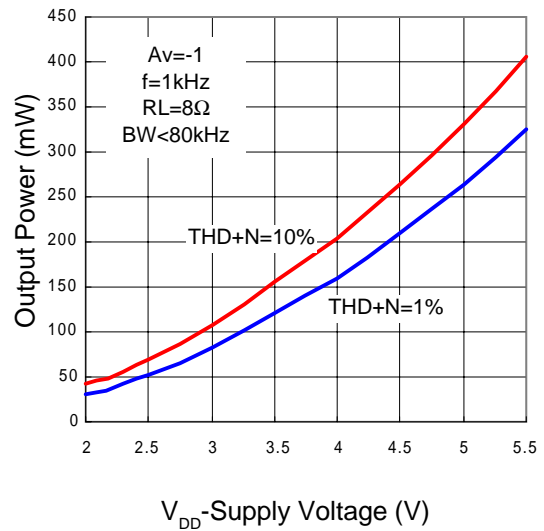
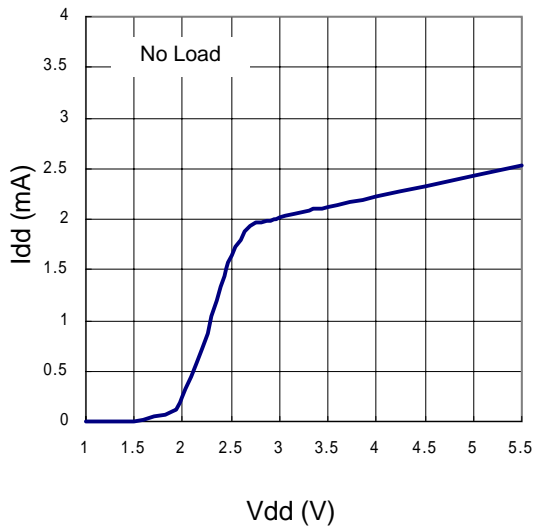
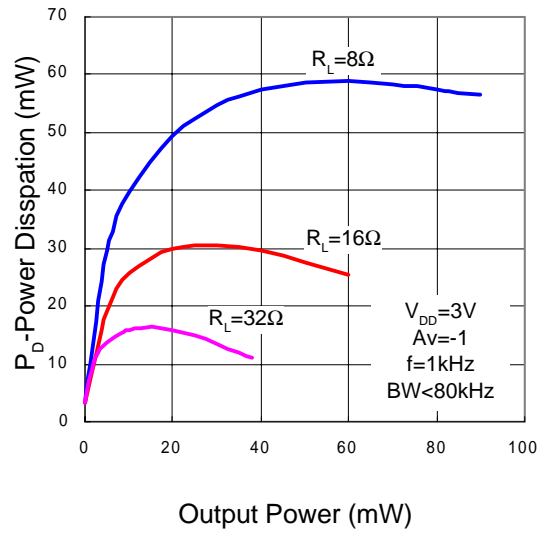
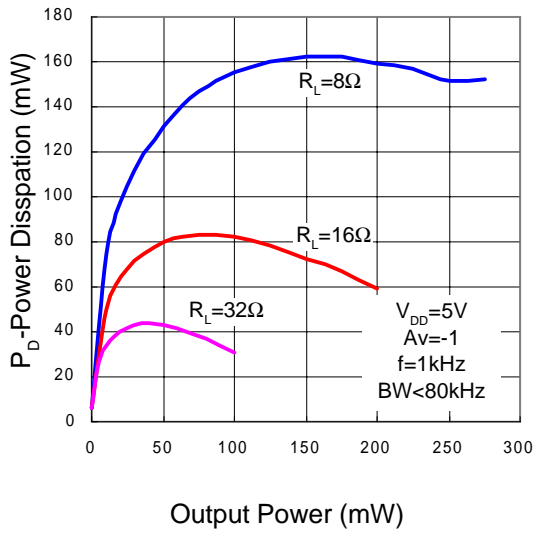
Typical Characteristics Cont.



Typical Characteristics Cont.

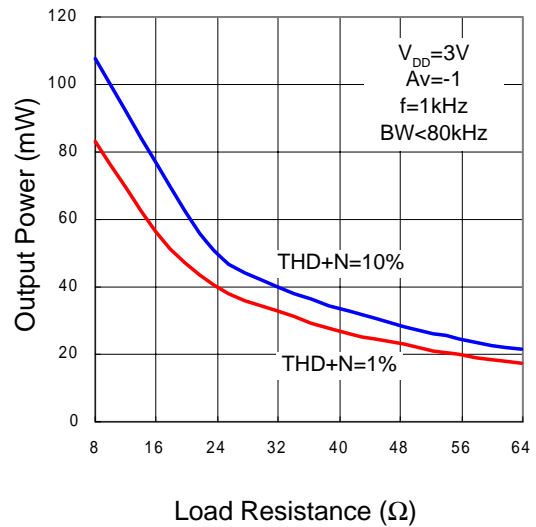
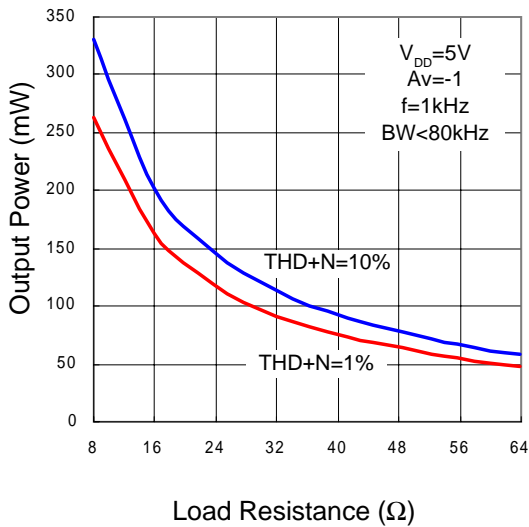
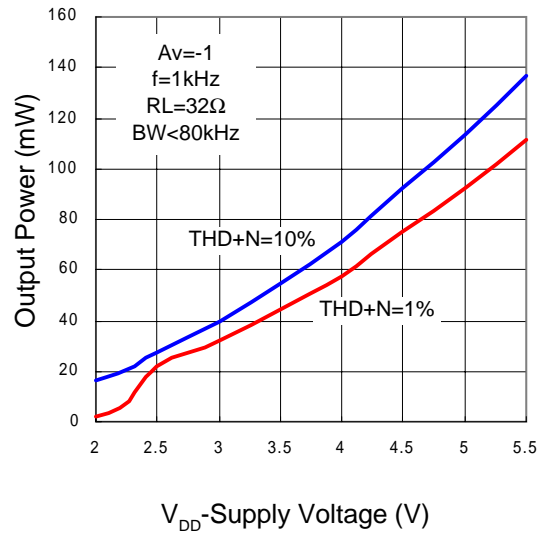
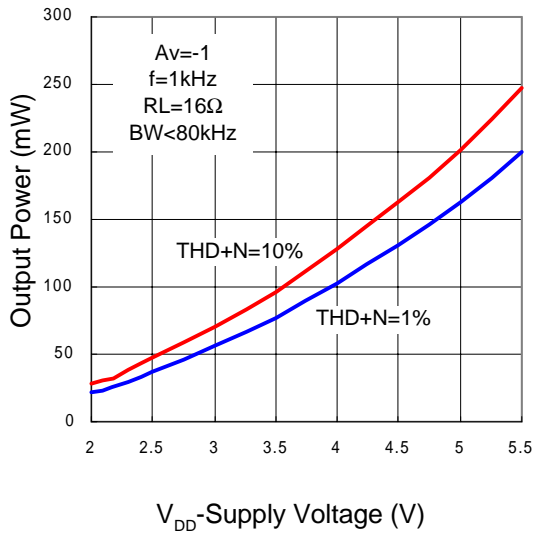


Typical Characteristics Cont.

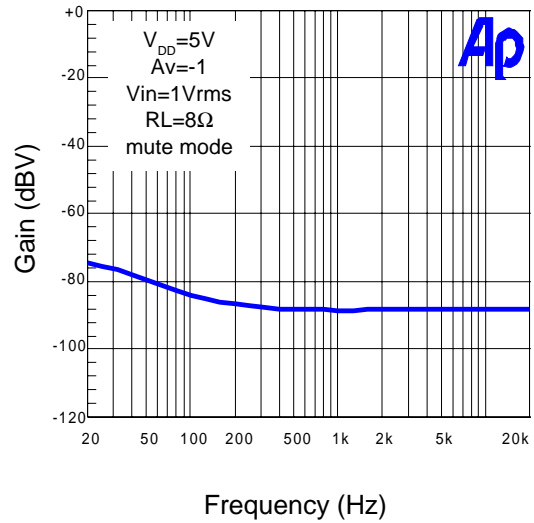
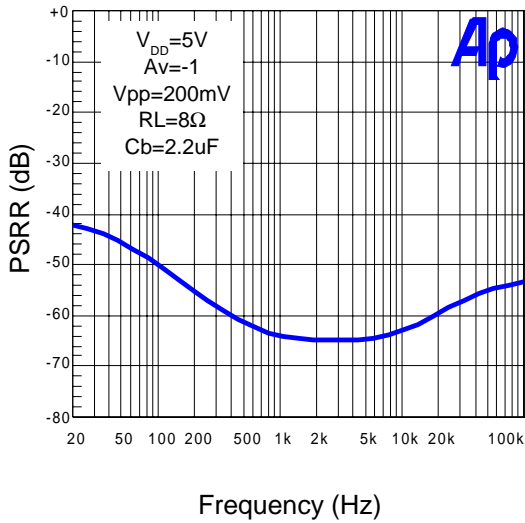
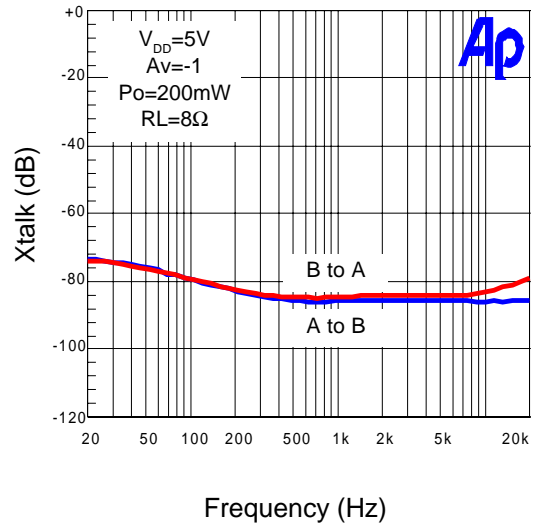
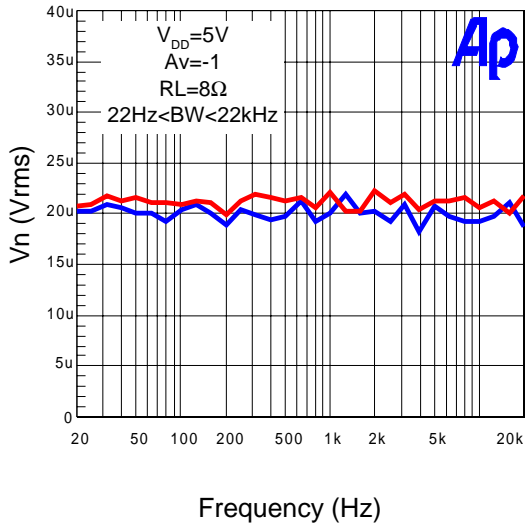




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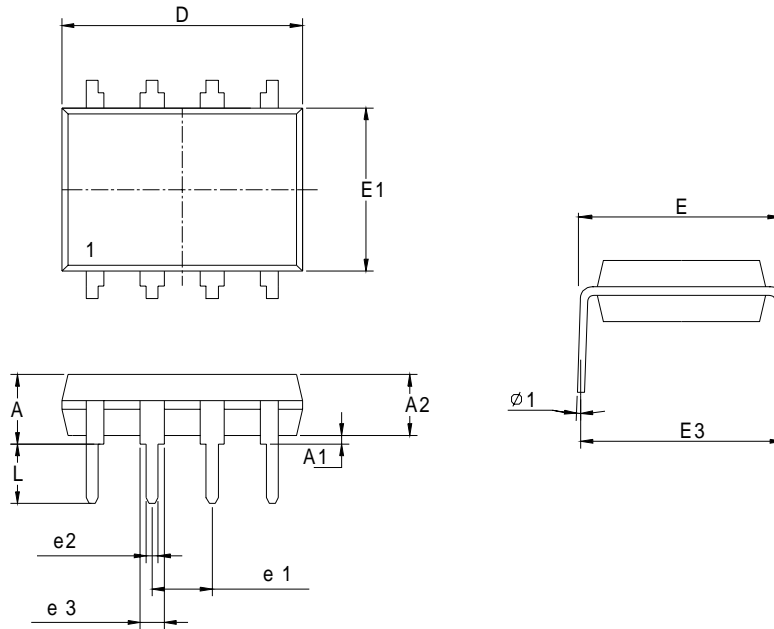


Typical Characteristics Cont.



## Packaging Information

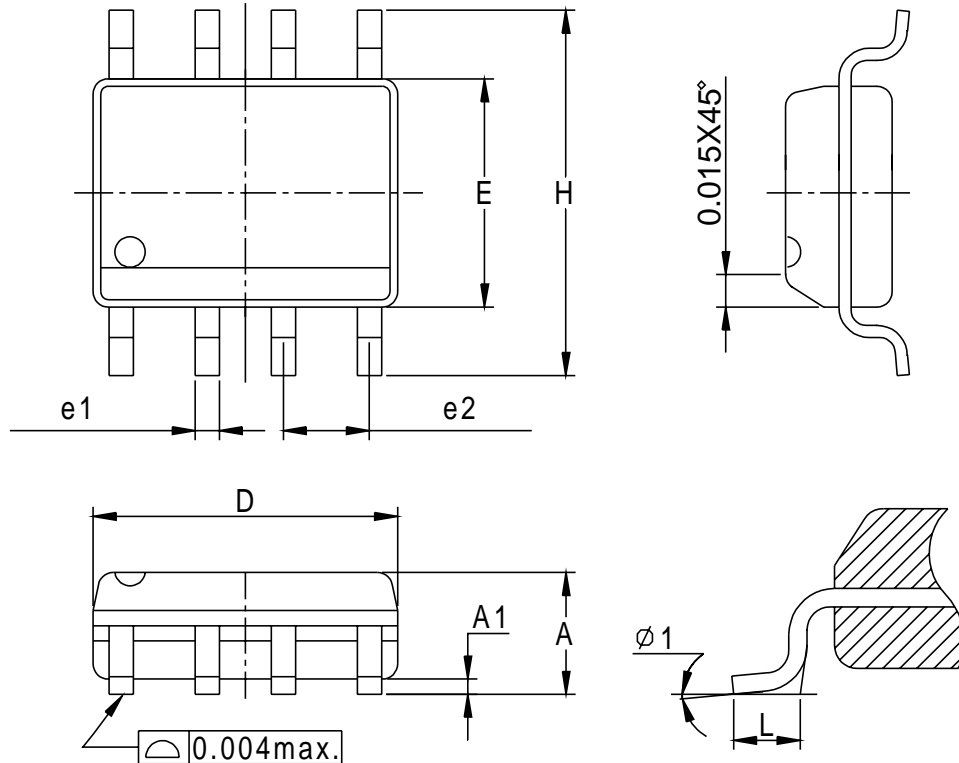
PDIP-8 pin ( Reference JEDEC Registration MS-001)



Dim	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A		5.33		0.210
A1	0.38		0.015	
A2	2.92	3.68	0.115	0.145
D	9.02	10.16	0.355	0.400
e1	2.54BSC		0.100BSC	
e2	0.36	0.56	0.014	0.022
e3	1.14	1.78	0.045	0.070
E	7.62 BSC		0.300 BSC	
E1	6.10	7.11	0.240	0.280
E3		10.92		0.430
L	2.92	3.81	0.115	0.150
ø 1	15°		15°	

## Packaging Information

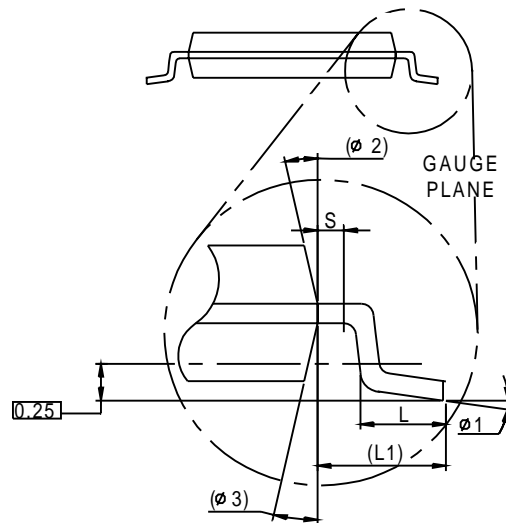
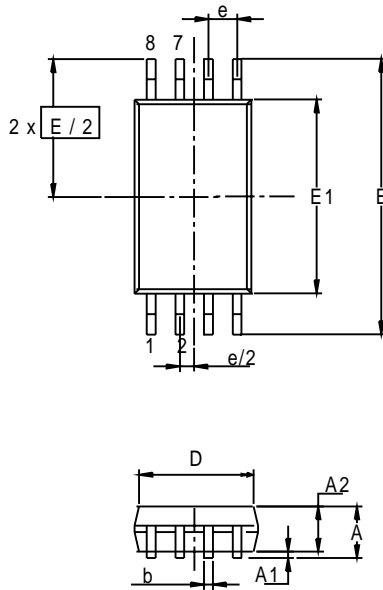
SOP-8 pin ( Reference JEDEC Registration MS-012)



Dim	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.35	1.75	0.053	0.069
A1	0.10	0.25	0.004	0.010
D	4.80	5.00	0.189	0.197
E	3.80	4.00	0.150	0.157
H	5.80	6.20	0.228	0.244
L	0.40	1.27	0.016	0.050
e1	0.33	0.51	0.013	0.020
e2	1.27BSC		0.50BSC	
φ 1	8°		8°	

## Packaging Information

TSSOP-8

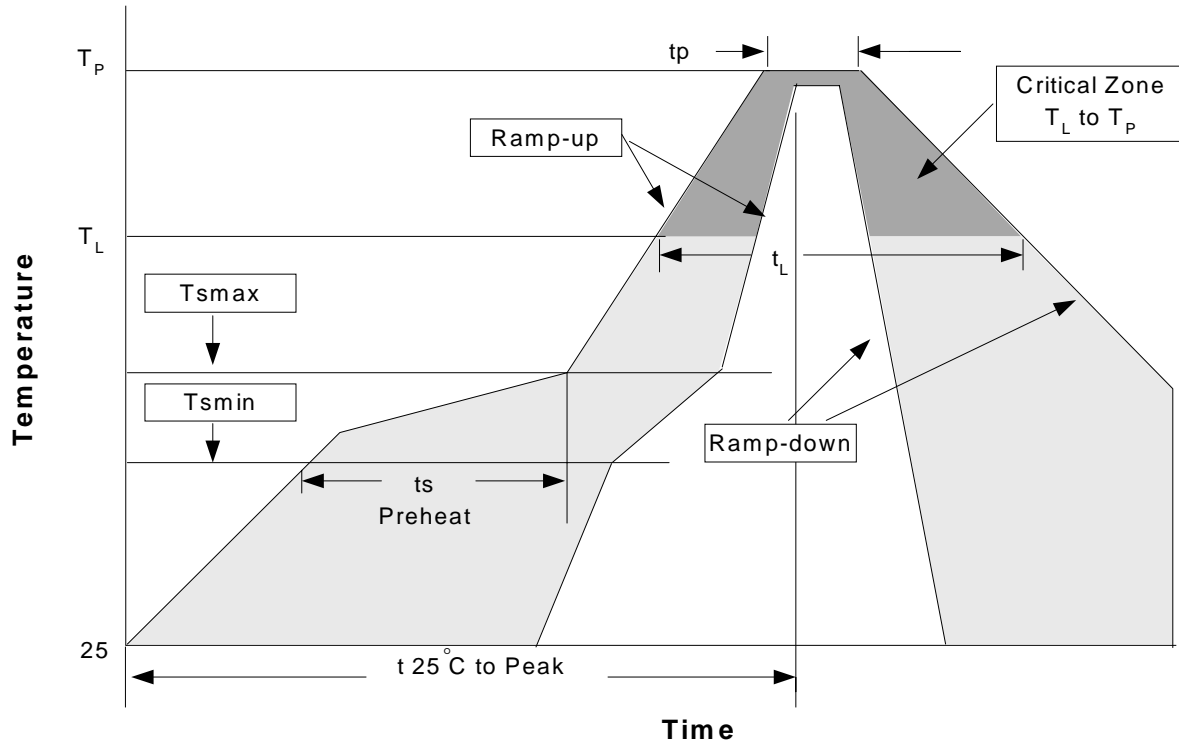


Dim	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A		1.2		0.047
A1	0.00	0.15	0.000	0.006
A2	0.80	1.05	0.031	0.041
b	0.19	0.30	0.007	0.012
D	2.9	3.1	0.114	0.122
e	0.65 BSC		0.026 BSC	
E	6.40 BSC		0.252 BSC	
E1	4.30	4.50	0.169	0.177
L	0.45	0.75	0.018	0.030
L1	1.0 REF		0.039 REF	
R	0.09		0.004	
R1	0.09		0.004	
S	0.2		0.008	
phi 1	0°	8°	0°	8°
phi 2	12° REF		12° REF	
phi 3	12° REF		12° REF	

## Physical Specifications

Terminal Material	Solder-Plated Copper (Solder Material : 90/10 or 63/37 SnPb), 100%Sn
Lead Solderability	Meets EIA Specification RSI86-91, ANSI/J-STD-002 Category 3.

### Reflow Condition (IR/Convection or VPR Reflow)



### Classification Reflow Profiles

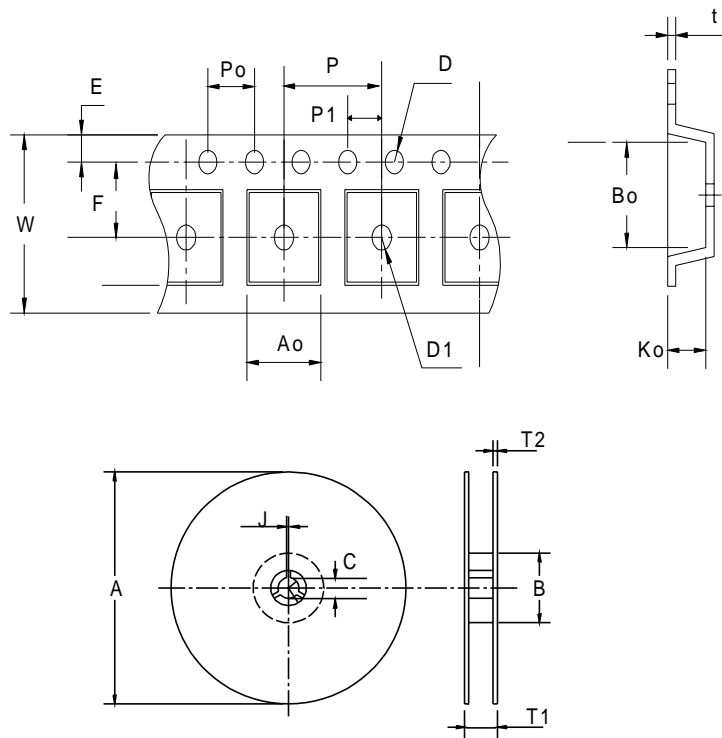
Profile Feature	Sn-Pb Eutectic Assembly		Pb-Free Assembly	
	Large Body	Small Body	Large Body	Small Body
Average ramp-up rate (T <sub>L</sub> to T <sub>P</sub> )	3°C/second max.		3°C/second max.	
Preheat				
- Temperature Min (T <sub>smin</sub> )	100°C		150°C	
- Temperature Mix (T <sub>smax</sub> )	150°C		200°C	
- Time (min to max)(t <sub>s</sub> )	60-120 seconds		60-180 seconds	
T <sub>smax</sub> to T <sub>L</sub>			3°C/second max	
- Ramp-up Rate				
T <sub>smax</sub> to T <sub>L</sub>				
- Temperature(T <sub>L</sub> )	183°C		217°C	
- Time (t <sub>L</sub> )	60-150 seconds		60-150 seconds	
Peak Temperature(T <sub>p</sub> )	225 +0/-5°C	240 +0/-5°C	245 +0/-5°C	250 +0/-5°C
Time within 5°C of actual Peak Temperature(t <sub>p</sub> )	10-30 seconds	10-30 seconds	10-30 seconds	20-40 seconds
Ramp-down Rate	6°C/second max.		6°C/second max.	
Time 25°C to Peak Temperature	6 minutes max.		8 minutes max.	

Note: All temperatures refer to topside of the package. Measured on the body surface.

## Reliability Test Program

Test item	Method	Description
SOLDERABILITY	MIL-STD-883D-2003	245°C, 5 SEC
HOLT	MIL-STD-883D-1005.7	1000 Hrs Bias @ 125°C
PCT	JESD-22-B,A102	168 Hrs, 100%RH, 121°C
TST	MIL-STD-883D-1011.9	-65°C~150°C, 200 Cycles
ESD	MIL-STD-883D-3015.7	VHBM > 2KV, VMM > 200V
Latch-Up	JESD 78	10ms, 1 <sub>tr</sub> > 100mA

## Carrier Tape & Reel Dimensions



Application	A	B	C	J	T1	T2	W	P	E
SOP- 8	330 ± 1	62 +1.5	12.75+ 0.15	2 ± 0.5	12.4 ± 0.2	2 ± 0.2	12± 0.3	8± 0.1	1.75±0.1
	F	D	D1	Po	P1	Ao	Bo	Ko	t
	5.5± 1	1.55 +0.1	1.55+ 0.25	4.0 ± 0.1	2.0 ± 0.1	6.4 ± 0.1	5.2± 0.1	2.1± 0.1	0.3±0.013
Application	A	B	C	J	T1	T2	W	P	E
TSSOP-8	330 ± 1	62 +1.5	12.75+ 0.15	2 + 0.5	12.4 ± 0.2	2 ± 0.2	12± 0.3	8± 0.1	1.75±0.1
	F	D	D1	Po	P1	Ao	Bo	Ko	t
	5.5 ± 0.1	1.5 + 0.1	1.5 + 0.1	4.0 ± 0.1	2.0 ± 0.1	7.0 ± 0.1	3.6 ± 0.3	1.6 ± 0.1	0.3±0.013

(mm)

## Cover Tape Dimensions

Application	Carrier Width	Cover Tape Width	Devices Per Reel
SOP- 8	12	9.3	2500
TSSOP- 8	12	9.3	2500

## Customer Service

### Anpec Electronics Corp.

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